

LINEAR TECHNOLOGY MATERIALS DECLARATION

ltc1387csw#pbf

(Engineering Calculation)

SOIC WIDE

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TOTAL MASS (g) : 0.542459

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.004891 | 1000000 | 9016.35449219 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.153163 | 975000 | 282349.59375 | | |
| | | Iron (Fe) | 7439-89-6 | 0.003770 | 24000 | 6949.83789062 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000047 | 300 | 86.642539978 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000110 | 700 | 202.780410767 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.157090 | 1000000 | 289588.84375 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.005974 | 1000000 | 11012.2246094 | | |
| | | External Plating Total: | | | | 0.005974 | 1000000 | 11012.2246094 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.001257 | 1000000 | 2317.22729492 | | |
| | | Internal Plating Total: | | | | 0.001257 | 1000000 | 2317.22729492 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.001276 | 750000 | 2352.25292969 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000425 | 250000 | 783.469787598 | | |
| Die Attach Total: | | | | 0.001701 | 1000000 | 3135.72265625 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.038213 | 103000 | 70444.0703125 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.332045 | 895000 | 612111.0625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000000 | 0 | 0 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000742 | 2000 | 1367.84606934 | | |
| | | Encapsulation Total: | | | | 0.371000 | 1000000 | 683923 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000546 | 1000000 | 1006.52825928 | | |
| | | | | | TOTAL MASS (g) : | 0.542459 | | |